



PRESS RELEASE

October, 20th 2026

SLAM CONFERENCE 2026 UNVEILS ITS PROGRAMME: *THREE DAYS AT THE HEART OF INNOVATION AND CHALLENGES IN THE ELECTRONICS INDUSTRY*

From 25 to 27 November 2026, Angers will host the first edition of SLAM Conference, the new technical event for the electronic board industry. With 41 talks, 2 round tables and about 50 speakers from industry and research, the event offers a state-of-the-art programme dedicated to technological innovation and to the challenges of competitiveness, reliability and sustainability in electronics.

Co-organised by Inventec Performance Chemicals, the IFTEC institute and We Network, with the support of the Fédération de l'Électronique Française, SLAM Conference presents a programme selected by a technical committee of 15 experts, favouring cutting-edge technological advances, research work and industrial feedback.

A TECHNICAL PROGRAMME EXPLORING THE MAJOR TRANSFORMATIONS IN ELECTRONICS

The programme covers six major themes across the electronic board value chain: design (DfX), PCBs and substrates, assembly processes, testing and Smart Factory, reliability and quality of assemblies, and sustainability and circularity. Among the many topics addressed, several major trends stand out.

Electronic design serving industrial performance.

The presentations will examine design from the perspective of industrialisation: taking manufacturing and testing constraints into account at an early stage (DfX), the role of artificial intelligence, thermal management, design for harsh environments, and small- and medium-volume production. The aim: more reliable, more robust and more competitive circuit boards.

Automation and artificial intelligence serving industrial performance.

The digitalisation of SMT lines, the automation of component flows and the integration of AI into manufacturing processes will be at the heart of discussions. Industrial case studies will illustrate these transformations in concrete terms.

New manufacturing and assembly technologies.

From vacuum soldering to new alloy formulations, including sintering, laser processes and additive PCB manufacturing, the talks will present new ways of meeting the growing performance requirements of electronic boards across all sectors.

Reliability of assemblies in demanding environments.

Resistance to thermomechanical stress, moisture protection, reliability of power modules and the lifespan of assemblies for space applications: these are all technical issues that will be explored through expert work and industrial applications.

Sustainability and circularity in electronics.

Alternative and bio-based materials, ecodesign, board recyclability, component reuse and the evolution of PFAS regulation: the programme will also give significant space to solutions that reduce the environmental footprint of electronics.

COMPETITIVENESS, SUPPLY CHAIN AND ENVIRONMENTAL IMPACT: COLLECTIVE CHALLENGES AT THE HEART OF THE DISCUSSIONS

Beyond the technical talks, several highlights will allow participants to step back and look at the strategic challenges facing the industry.

On Thursday 26 November, Christian Maudet from Thales will open the day with a keynote entitled “Electronic boards: can we be collectively competitive?”, raising the question of the levers of competitiveness across the industrial ecosystem.

On Friday 27 November, a round table devoted to the PCB supply chain will bring together industry players to discuss current challenges in the printed circuit supply chain and issues of sovereignty.

A second round table will focus on environmental data and life cycle assessment (LCA), two essential issues in supporting the environmental transition of the electronics industry.

A UNIFYING EVENT FOR ELECTRONICS EXPERTS AND MANUFACTURERS

For three days, SLAM Conference will bring together in Angers players from across the electronic board value chain, from design to assembly: major industrial groups, specialised companies, technical centres and research organisations.

The event will also make ample room for networking, with an exhibition area dedicated to industrial innovations and solutions, a welcome reception on 25 November at the Angers Museum of Fine Arts (Musée des Beaux-Arts) and a gala dinner on 26 November at the Greniers Saint-Jean.

An event backed by industry players.

For this first edition, SLAM Conference benefits from the support of several leading electronics companies, committed alongside the organisers to making it a place for knowledge sharing and professional networking.

Among them, *Lacroix, Thales and Micronique*, as well as *Glenair, C.I.F, Alliance Electronics, Metcal, Serma Technologies* and *Global Electronic Association*.

PROGRAMME AND REGISTRATION

SLAM Conference 2026 — 25 to 27 November 2026

Centre de Congrès Jean-Monnier, Angers

The detailed programme, speakers and registration details are available on the official website :

www.slam-conference-electronique.fr

Registrations are open until 18 November 2026.

ABOUT CO-ORGANISERS

We Network is both the leading technical centre for electronic assembly and a cluster of manufacturers, bringing together an ecosystem of 170 stakeholders from industry, research and education. As a trusted third party, We Network supports start-ups, SMEs and mid-market companies in accelerating and securing their industrial projects.

Inventec Performance Chemicals is a supplier and producer of soldering, cleaning, coating and cooling materials for electronic applications across multiple sectors, ranging from medical and defence to automotive, aerospace and semiconductors. With over 150 years of history as part of the Dehon Group, Inventec has always strived to anticipate regulatory requirements, thereby guaranteeing its customers reliable and sustainable solutions.

IFTEC (IFTEC Institute) is a resource and training centre, established in 1967, specialising in the techniques and technologies of printed circuit board manufacturing. A leading provider of IPC training and certification, having trained over 26,000 engineers, technicians and operators over the last 20 years, the institute enhances the skills of professionals in the electronics industry through its workshops equipped with professional-grade equipment. IFTEC also offers expert analysis services in its testing laboratory.

PRESS CONTACT

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The SLAM Conference is co-organised by IFTEC, Inventec Performance Chemicals and We Network, with the support of the French Electronics Federation.

SLAM conference is an event co-organised by



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From the 25th to the 27th of November 2026 in Angers